ABSTRACT

A photosensitive resin composition, characterized in comprising:

(A) a polymer having a carbon hydrocarbon double bond and carboxyl group, formed by the reaction of an acid anhydride with the reaction product of an epoxy compound having a structure wherein a glycidyloxy group is bonded to a main chain comprising an aromatic ring, an alkylene group and an oxygen atom, with an unsaturated carboxyl compound having a carbon-carbon double bond and a carboxyl group, (B) a photopolymerizable monomer, (C) a radical photopolymerization initiator, and (D) a curing agent having reactivity with the functional groups of the polymer and/or the photopolymerizable monomer. Using this photosensitive resin composition, a solder resist having excellent resolution, adhesion, PCT resistance, electrical corrosion resistance, heat resistance and thermal impact resistance can be formed.